Special Issue

Recent Advances in Soft Electronic Materials and Devices

Message from the Guest Editor

Notable progress have been made in developing soft electronic materials and devices. Owing to their superior mechanical characteristics, that is, being soft, flexible, bendable, stretchable, twistable, etc., soft electronics hold potential to be implemented in health monitors, medical implants, artificial skins, human–machine interfaces, etc. Additionally, as wearable electronic devices become more prevalent, the need for the industrialization of soft electronics grows urgent, indicating that the soft electronics industry will not only remain in the realm of laboratories but will also reach the real world. With the rapid development of soft science and technologies, this Special Issue aims to collect articles on the latest progress in soft materials and electronics in sensing-, energy-, e-skin-, robot-, health-, and medical-related applications. This Special Issue also covers a broad range of fundamental concepts, as well as experimental and theoretical studies, related to flexibility and stretchability, as well as applications with new ideas for device architecture and new approaches for device performance.

Guest Editor

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